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For Immediate Release

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Seika Machinery Highlights Malcom SRS-200 Reflow Simulator for Large BGA Evaluation

TORRANCE, CA — November 2026 — Seika Machinery, Inc., a leading provider of advanced machinery, materials and engineering services, announces that it highlighted Malcom's new SRS-200 Reflow Simulator during SMTA International 2026, introducing a system designed to evaluate the reflow behavior of large ball grid array (BGA) packages, including those increasingly used in data center applications.

In a video interview recorded at the show by *Global SMT & Packaging* Editor Trevor Galbraith, Charlie Fujikawa, Senior Sales Engineer at Seika Machinery, discussed the SRS-200's capabilities and the improvements it brings to reflow process evaluation.



The SRS-200 features a single-zone design that simulates a complete reflow temperature profile within one chamber. Unlike systems that require samples to travel through multiple heating zones, the SRS-200 keeps the sample stationary throughout the process. This approach allows the system to record video of solder ball collapse while simultaneously measuring sample warpage, providing engineers with valuable insight into component behavior under reflow conditions.

A key advancement over its predecessor is the SRS-200's substantially larger sample capacity. The system accommodates samples measuring up to 200 x 200 mm, compared with the previous 50 x 50 mm limit. This expanded capacity addresses the growing need to evaluate larger electronic assemblies and advanced BGA packages, particularly those used in high-performance computing and data center applications.

By combining full-profile reflow simulation, real-time video observation of ball collapse and warpage measurement in a single chamber, the SRS-200 provides engineers with a tool for examining solder joint behavior and evaluating assembly characteristics under controlled thermal conditions.

For a closer look at the new Malcom SRS-200, watch the video interview with Charlie Fujikawa, conducted by Trevor Galbraith of *Global SMT & Packaging* during SMTA International 2026 at https://www.youtube.com/watch?v=a0Oka3srJeI.

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For more information about Malcom's SRS-200 Reflow Simulator, contact Michelle Ogihara at 310-540-7310; e-mail michelle@seikausa.com; or visit www.seikausa.com.

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About Seika Machinery, Inc.
Seika Machinery, Inc. (SMI) is a subsidiary of Seika Corporation, Japan and member of the Mitsubishi Global Group. SMI provides electronics manufacturers with advanced machinery, superior materials and engineering services.